TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS240A

September 1998 - Revised May 2000

8-Bit Serial-In/Parallel-Out Shift Register

Features

- **Buffered Inputs**
- **Typical Propagation Delay**
  - **6ns at V_{CC} = 5V, T_A = 25°C, C_L = 50pF**
- **Exceeds 2kV ESD Protection MIL-STD-883, Method 3015**
- **SCR-Latchup-Resistant CMOS Process and Circuit Design**
- **Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption**
- **Balanced Propagation Delays**
- **AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply**
- **±24mA Output Drive Current**
  - **Fanout to 15 FAST™ ICs**
  - **Drives 50Ω Transmission Lines**

Description

The 'AC164 and 'ACT164 are 8-bit serial-in/parallel-out shift registers with asynchronous reset that utilize Advanced CMOS Logic technology. Data is shifted on the positive edge of the clock (CP). A LOW on the Master Reset ($\overline{MR}$) pin resets the shift register and all outputs go to the LOW state regardless of the input conditions. Two Serial Data inputs (DS1 and DS2) are provided; either one can be used as a Data Enable control.
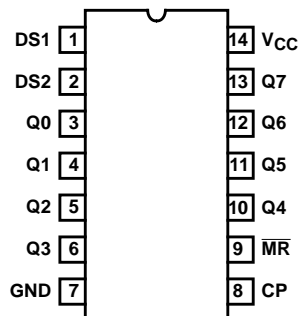
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54AC164F3A	-55 to 125	14 Ld CERDIP
CD74AC164E	-55 to 125	14 Ld PDIP
CD74AC164M	-55 to 125	14 Ld SOIC
CD54ACT164F3A	-55 to 125	14 Ld CERDIP
CD74ACT164E	-55 to 125	14 Ld PDIP
CD74ACT164M	-55 to 125	14 Ld SOIC

NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.
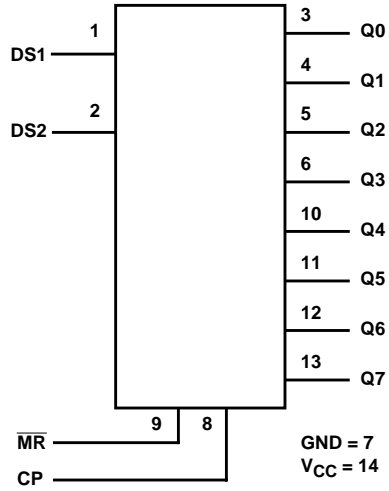
Pinout

**CD54AC164, CD54ACT164
(CERDIP)
CD74AC164, CD74ACT164
(PDIP, SOIC)
TOP VIEW**

DS1	1	14 V_{CC}
DS2	2	13 Q7
Q0	3	12 Q6
Q1	4	11 Q5
Q2	5	10 Q4
Q3	6	9 $\overline{MR}$
GND	7	8 CP

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Functional Diagram

MODE SELECT - TRUTH TABLE

	INPUTS				OUTPUTS	
OPERATING MODE	$\overline{MR}$	**CP**	**DS1**	**DS2**	**Q0**	**Q1 - Q7**
RESET (CLEAR)	L	X	X	X	L	L - L
SHIFT	H	↑	l	l	L	q0 - q6
	H	↑	l	h	L	q0 - q6
	H	↑	h	l	L	q0 - q6
	H	↑	h	h	H	q0 - q6

H = HIGH voltage level steady state.
L = LOW voltage level steady state.
h = HIGH voltage level one setup time prior to the LOW-to_HIGH clock transition.
l = LOW voltage level one setup time prior to the LOW-to-HIGH clock transition.
X = Don't care.
q = Lowercase letters indicate the state of the referenced output prior to the LOW-to-HIGH clock transition.
↑ = LOW-to-HIGH clock transition.

CD54/74AC164, CD54/74ACT164

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . -0.5V to 6V
DC Input Diode Current, I_{IK}
   For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . . ±20mA
DC Output Diode Current, I_{OK}
   For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . . ±50mA
DC Output Source or Sink Current per Output Pin, I_O
   For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . . ±50mA
DC V_{CC} or Ground Current, $I_{CC \; or} \; I_{GND}$ (Note 3) . . . . ±100mA

Thermal Information

Thermal Resistance (Typical, Note 5) θ_{JA} (^{O}C/W)
   PDIP Package   90
   SOIC Package   175
Maximum Junction Temperature (Plastic Package) . . . . 150°C
Maximum Storage Temperature Range . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . 300°C
  (SOIC - Lead Tips Only)

Operating Conditions

Temperature Range, T_A . . . . -55°C to 125°C
Supply Voltage Range, V_{CC} (Note 4)
   AC Types. . . . . .1.5V to 5.5V
   ACT Types . . . . .4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O . . . . 0V to V_{CC}
Input Rise and Fall Slew Rate, dt/dv
   AC Types, 1.5V to 3V . . . . 50ns (Max)
   AC Types, 3.6V to 5.5V. . . . . 20ns (Max)
   ACT Types, 4.5V to 5.5V. . . . . 10ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

3. For up to 4 outputs per device, add ±25mA for each additional output.

4. Unless otherwise specified, all voltages are referenced to ground.

5. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS V_I (V)	TEST CONDITIONS I_O (mA)	V_{CC} (V)	25°C MIN	25°C MAX	-40°C TO 85°C MIN	-40°C TO 85°C MAX	-55°C TO 125°C MIN	-55°C TO 125°C MAX	UNITS
AC TYPES											
High Level Input Voltage	V_{IH}	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	V_{IL}	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	V_{OH}	V_{IH} or V_{IL}	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS V_I (V)	TEST CONDITIONS I_O (mA)	V_{CC} (V)	25°C MIN	25°C MAX	-40°C TO 85°C MIN	-40°C TO 85°C MAX	-55°C TO 125°C MIN	-55°C TO 125°C MAX	UNITS
Low Level Output Voltage	V_{OL}	V_{IH} or V_{IL}	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I_I	V_{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Quiescent Supply Current MSI	I_{CC}	V_{CC} or GND	0	5.5	-	8	-	80	-	160	µA
ACT TYPES											
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V_{OH}	V_{IH} or V_{IL}	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V_{OL}	V_{IH} or V_{IL}	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I_I	V_{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Quiescent Supply Current MSI	I_{CC}	V_{CC} or GND	0	5.5	-	8	-	80	-	160	µA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI_{CC}	V_{CC} -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

NOTES:

6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

7. Test verifies a minimum 50Ω transmission-line-drive capability at 85°C, 75Ω at 125°C.

ACT Input Load Table

INPUT	UNIT LOAD
DS1, DS2	0.5
$\overline{MR}$	0.74
CP	0.71

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

Prerequisite For Switching Function

PARAMETER	SYMBOL	V_{CC} (V)	-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	
AC TYPES							
Max. Clock Frequency	f_{MAX}	1.5	7	-	6	-	MHz
		3.3 (Note 9)	62	-	54	-	MHz
		5 (Note 10)	86	-	75	-	MHz
$\overline{MR}$ Pulse Width	t_W	1.5	49	-	56	-	ns
		3.3	5.5	-	6.3	-	ns
		5	3.9	-	4.5	-	ns
CP Pulse Width	t_W	1.5	73	-	84	-	ns
		3.3	8.2	-	9.4	-	ns
		5	5.9	-	6.7	-	ns
Set-up Time	t_{SU}	1.5	27	-	31	-	ns
		3.3	3.1	-	3.5	-	ns
		5	2.2	-	2.5	-	ns
Hold Time	t_H	1.5	27	-	31	-	ns
		3.3	3.1	-	3.5	-	ns
		5	2.2	-	2.5	-	ns
$\overline{MR}$ to CP Removal Time	t_{REM}	1.5	1	-	1	-	ns
		3.3	1	-	1	-	ns
		5	1	-	1	-	ns
ACT TYPES							
Max. Clock Frequency	f_{MAX}	5 (Note 10)	80	-	70	-	MHz
$\overline{MR}$ Pulse Width	t_W	5	3.9	-	4.5	-	ns
CP Pulse Width	t_W	5	6.2	-	7.1	-	ns
Set-up Time	t_{SU}	5	2.2	-	2.5	-	ns
Hold Time	t_H	5	2.6	-	3	-	ns
$\overline{MR}$ to CP Removal Time	t_{REM}	5	0	-	0	-	ns

Switching Specifications Input t_r, t_f = 3ns, C_L = 50pF (Worst Case)

PARAMETER	SYMBOL	V_{CC} (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
AC TYPES									
Propagation Delay, CP to Qn	t_{PLH}, t_{PHL}	1.5	-	-	143	-	-	157	ns
		3.3 (Note 9)	4.5	-	15.9	4.4	-	17.5	ns
		5 (Note 10)	3.2	-	11.4	3.1	-	12.5	ns

Switching Specifications Input t_r, t_f = 3ns, C_L = 50pF (Worst Case) **(Continued)**

PARAMETER	SYMBOL	V_{CC} (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
Propagation Delay, $\overline{MR}$ to Qn	t_{PLH}, t_{PHL}	1.5	-	-	158	-	-	174	ns
		3.3	5	-	17.7	4.9	-	19.5	ns
		5	3.6	-	12.6	3.5	-	13.9	ns
Input Capacitance	C_I	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C_{PD} (Note 11)	-	-	150	-	-	-	150	-	pF
ACT TYPES									
Propagation Delay, CP to Qn	t_{PLH}, t_{PHL}	5 (Note 10)	3.8	-	13.5	3.7	-	14.9	ns
Propagation Delay, $\overline{MR}$ to Qn	t_{PLH}, t_{PHL}	5	4.1	-	14.4	4	-	15.8	ns
Input Capacitance	C_I	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C_{PD} (Note 11)	-	-	150	-	-	-	150	-	pF

NOTES:

8. Limits tested at 100%.

9. 3.3V Min at 3.6V, Max at 3V.

10. 5V Min at 5.5V, Max at 4.5V.

11. C_{PD} is used to determine the dynamic power consumption per device.
   $P_D = C_{PD}V_{CC}^2 f_i \Sigma (C_L V_{CC}^2 f_o) + V_{CC} \Delta I_{CC}$, where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, V_{CC} = supply voltage.
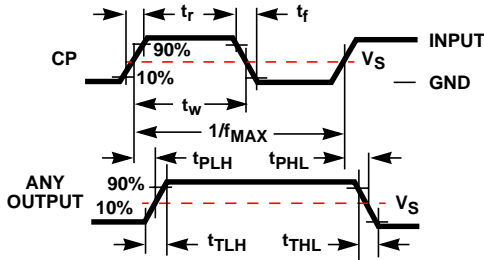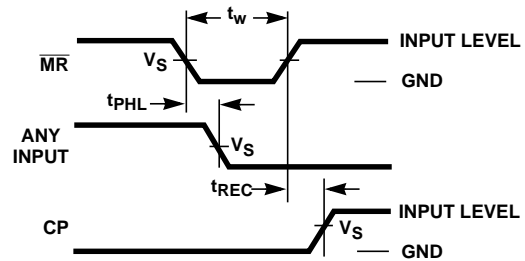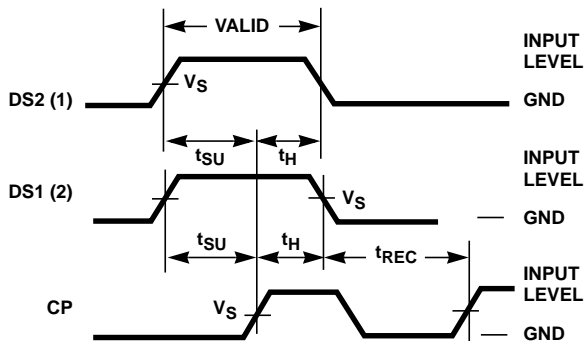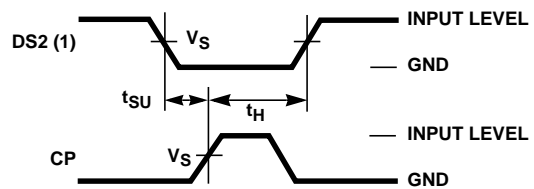

FIGURE 1.

FIGURE 2.

FIGURE 3.

FIGURE 4.
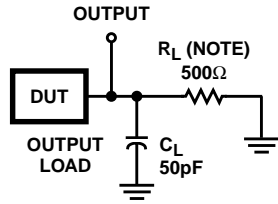
NOTE: For AC Series Only: When V_{CC} = 1.5V, R_L = 1kΩ.

	AC	ACT
Input Level	V_{CC}	3V
Input Switching Voltage, V_S	0.5 V_{CC}	1.5V
Output Switching Voltage, V_S	0.5 V_{CC}	0.5 V_{CC}

FIGURE 5. PROPAGATION DELAY TIMES

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54AC164F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC164F3A	Samples
CD54ACT164F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT164F3A	Samples
CD74AC164E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC164E	Samples
CD74AC164M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC164M	Samples
CD74ACT164E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT164E	Samples
CD74ACT164M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT164M	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54AC164, CD54ACT164, CD74AC164, CD74ACT164 :

● Catalog : CD74AC164, CD74ACT164

● Military : CD54AC164, CD54ACT164

NOTE: Qualified Version Definitions:

    ● Catalog - TI's standard catalog product

    ● Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC164M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74ACT164M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC164M96	SOIC	D	14	2500	356.0	356.0	35.0
CD74ACT164M96	SOIC	D	14	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

TUBE

T - Tube height

L - Tube length

W - Tube width

B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74AC164E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC164E	N	PDIP	14	25	506	13.97	11230	4.32
CD74ACT164E	N	PDIP	14	25	506	13.97	11230	4.32
CD74ACT164E	N	PDIP	14	25	506	13.97	11230	4.32

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

PIN 1 ID
(OPTIONAL)

A

1

14

12X .100
[2.54]

7

8

.754-.785
[19.15-19.94]

B

.245-.283
[6.22-7.19]

4X .005 MIN
[0.13]

.015-.060 TYP
[0.38-1.52]

14X .045-.065
[1.15-1.65]

14X .014-.026
[0.36-0.66]

⊕ .010 [0.25] C A B

.2 MAX TYP
[5.08]

.13 MIN TYP
[3.3]

C

SEATING PLANE

.308-.314
[7.83-7.97]
AT GAGE PLANE

.015
[0.38]

GAGE PLANE

0°-15°
TYP

14X .008-.014
[0.2-0.36]

4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

J0014A

CERAMIC DUAL IN LINE PACKAGE

(.300) TYP
[7.62]

SEE DETAIL A

SEE DETAIL B

1

14

12X (.100)
[2.54]

SYMM
℄

14X (∅ .039)
[1]

7

8

SYMM
℄

LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

.002 MAX
[0.05]
ALL AROUND

(.063)
[1.6]

SOLDER MASK
OPENING

METAL

(R.002) TYP
[0.05]

DETAIL A
SCALE: 15X

METAL

(∅ .063)
[1.6]

SOLDER MASK
OPENING

.002 MAX
[0.05]
ALL AROUND

DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

TEXAS
INSTRUMENTS
www.ti.com

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
⟁C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⟁D

1   7

Pin 1
Index Area

0.050 (1,27)   0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
        ⟁C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
        ⟁D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E. Reference JEDEC MS−012 variation AB.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

Example
Solder Mask Opening
(See Note E)

0,60

1,55

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Publication IPC−7351 is recommended for alternate designs.
        D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
            contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
        E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

TEXAS
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N (R−PDIP−T**)

16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

	PINS **	14	16	18	20
DIM					
A MAX		0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN		0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION		AA	BB	AC	AD

0.260 (6,60)
0.240 (6,10)

0.070 (1,78)
0.045 (1,14)

0.045 (1,14)
0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
        D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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